



LIGHTWAVELOGIC™

Faster by Design

Advancing integrated photonics with electro-optic polymer modulators

Michael Lebby, CEO

14th September 2021, Market Focus

The information in this presentation may contain forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. You can identify these statements by use of the words "may," "will," "should," "plans," "explores," "expects," "anticipates," "continue," "estimate," "project," "intend," and similar expressions. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those projected or anticipated. These risks and uncertainties include, but are not limited to, general economic and business conditions, effects of continued geopolitical unrest and regional conflicts, competition, changes in technology and methods of marketing, delays in completing various engineering and manufacturing programs, changes in customer order patterns, changes in product mix, continued success in technological advances and delivering technological innovations, shortages in components, production delays due to performance quality issues with outsourced components, and various other factors beyond the Company's control.

Lightwave Logic overview

- **Successfully up-listed to NASDAQ in 1st Sept 2021**

- Organic up-list (no reverse split)
- Invited to speak at investment conferences
- Invited to speak at international technical conferences

- **Strong Balance Sheet**

- Looking to strengthen for product acceleration to market

- **Very strong IP and patent position**

- Over 70+ patents & patent applications
- Freedom of manufacturing

Lightwave Logic NASDAQ: LWLG

Share Price ¹	\$9.80
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Market Cap ¹	\$1.06B
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Cash ²	\$13.9M
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Total Liabilities ¹	\$1.0M
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Shares Outstanding	107.8M
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Headquarters	Englewood, CO
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1) As of 2nd September, 2021

2) As of 16th August, 2021

Company Headquarters



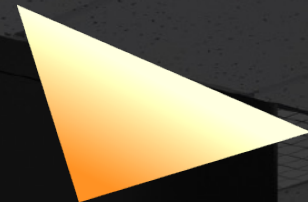
Ringling the bell at NASDAQ (last week)



NASDAQ energy.....



Closing the market 10th September at 4pm East coast time precisely...



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Applications & Markets



Proprietary EO polymer technology

Starting With Fiber Communications, Our Technology Can be Extended To More Applications

Lightwave's proprietary, internally-engineered organic polymer materials use **less power & increase data throughput in existing network infrastructure**

How? By developing **ultrafast optical modulators** using its polymers that convert ultra-high-speed electrical data to light that travels over existing fiber-optic networks



Current Applications

- Initial prototypes cover today's state-of-the-art 50/100 Gbaud and the next-generation 400 Gbaud fiber optic applications
- Target speeds up to 100 & 200 Gigabaud per device, 800 & 1600 Gbit/s in aggregate with low voltage
- Modulators can be integrated to make more complex chips such as multi-channel modulators for higher aggregate speed



Future Applications

- Potential development of new polymer materials for specific **non-communication applications** such as: LIDAR automotive, sensing, displays, high speed computational processing, crypto, medical, and areas **where light needs to be switched quickly at low power**

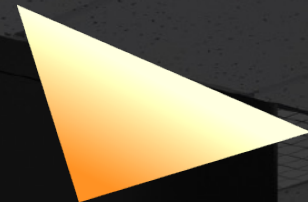
Our polymers enable faster devices, low power solutions today

Photonics markets broaden significantly

Photonics applications	Photonics → 2030 (rough forecasts*)	Opportunity for PICs (polymer & silicon photonics/InP)
5G systems/back haul/RF	~\$4-10B	Yes
Display/project	~\$5-20B	Yes
Automotive (LIDAR)	~\$20-50B	Yes
Optical sensing/3D	~\$2-5B	Yes
Bio-photonic sensing	~\$2-5B	Yes
Medical	~\$5-10B	Yes
Instrumentation	~\$1-3B	Yes
Fiber comms	~\$40-60B	Existing
HPC/computational/AI	~\$10-20B	Existing
DCI/datacenter	~\$20-30B	Existing

Photonics becomes ubiquitous during the next decade

Source: *Many market forecasts predict huge photonics opportunities; Oculi



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Technologies

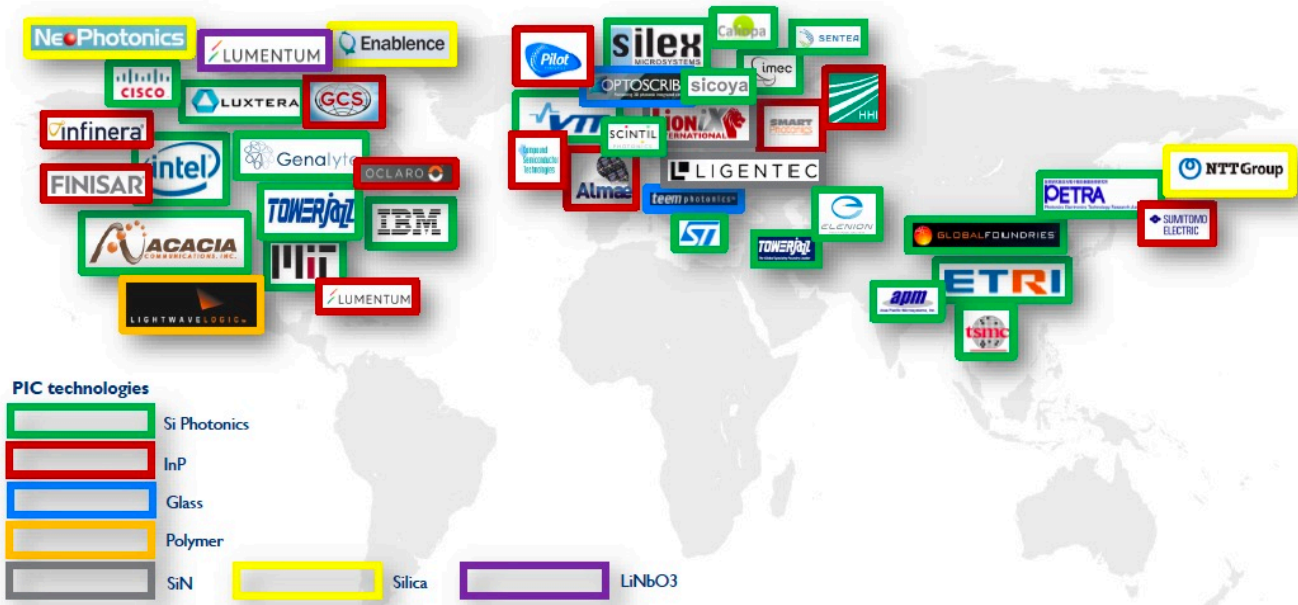


- Historic incumbent:
 - InP (Indium Phosphide)
 - GaAs (Gallium Arsenide)
- New incumbent:
 - SiP (Silicon photonics)
- ***New platforms and hybrid accelerators for PICs***
 - *Polymer, dielectrics, glass, lithium niobate thin film, plasmonic, barium titanate, silica, glass, germanium etc.*

Hybrid PICs are the future!

Sample global players and their PIC platforms

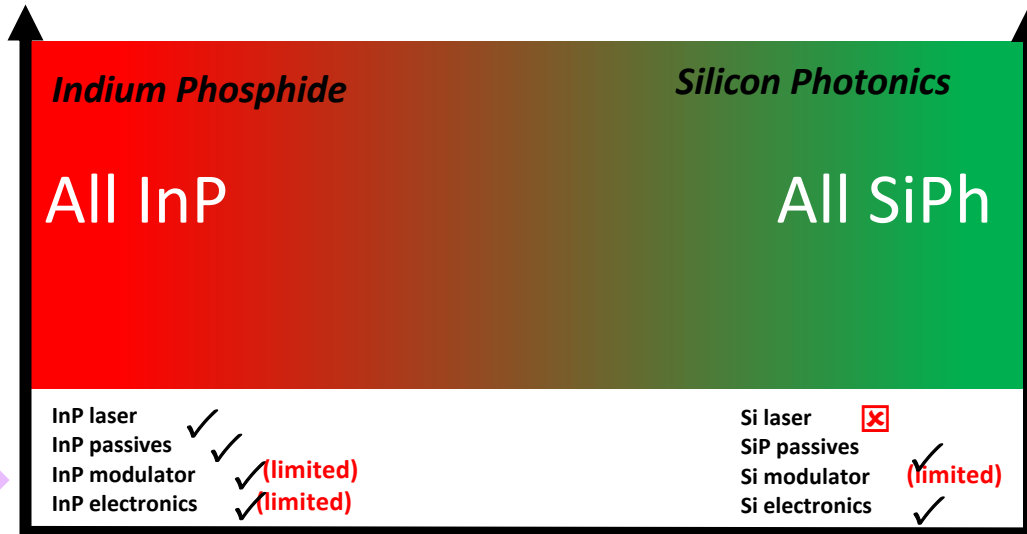
- Growth of Silicon photonics
- Trend towards hybrid platforms for PICs
- What combinations of technology make sense for *hybrid* PICs?



Challenge is to further PIC performance with other materials → hybrid PICs

Industry has 2 incumbent PICs, however...

Incumbent *Incumbent*

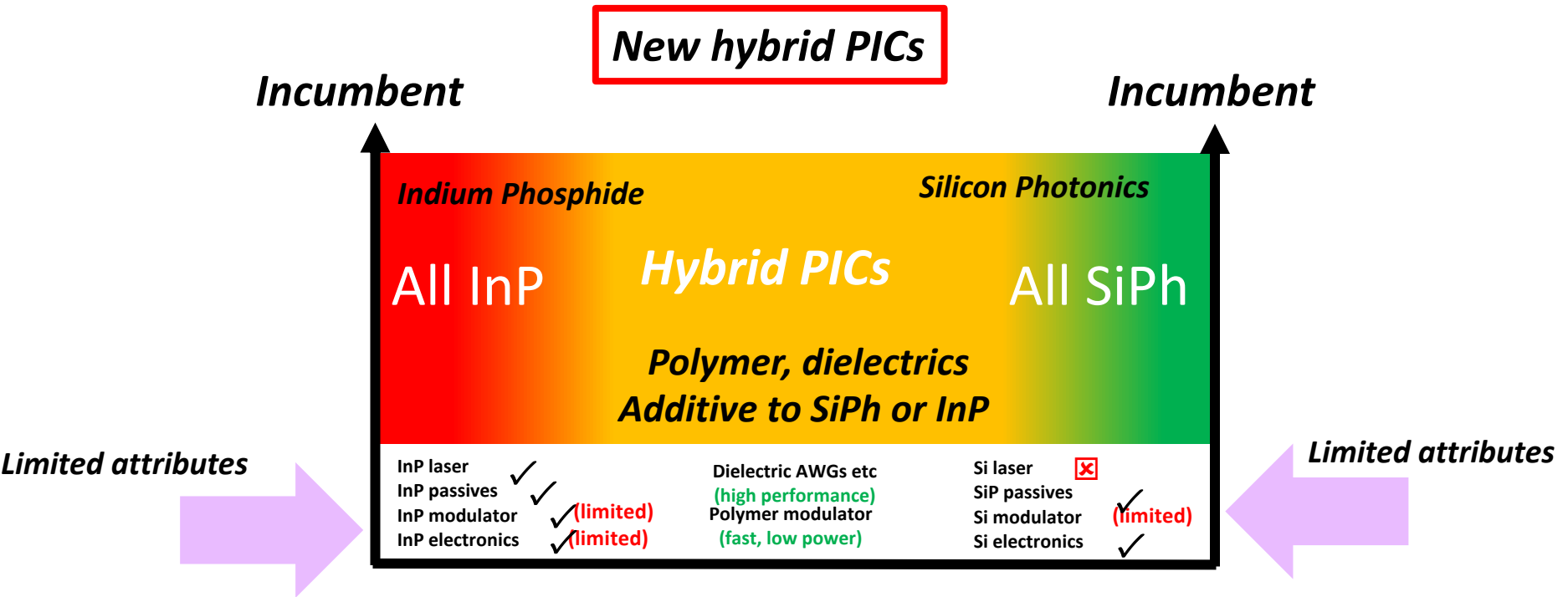


Limited attributes

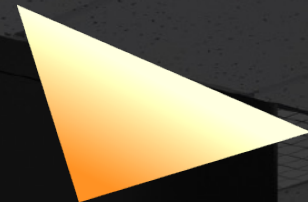
Limited attributes

Incumbent technologies can't do everything...

Hybrid PICs increase performance...



Hybrid PICs can boost performance of PICs



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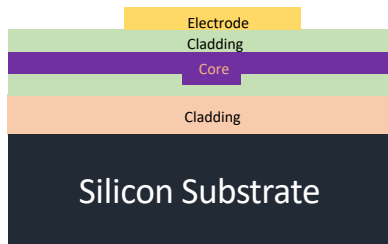
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E-O polymers



Additive to semiconductor platforms (silicon photonics, InP, GaAs...) to enhance performance

Polymer Stack™

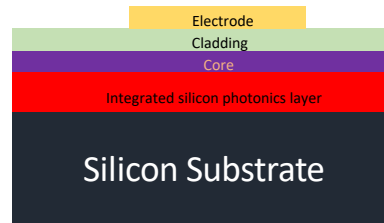


Classic!

Polymer stack modulator

- 3-layer polymer stack waveguides
- Linear Pockel's effect phase modulator (or Amplitude modulator if in Mach-Zehnder)
- Excellent high-speed performance (>100 GHz), low voltage ($\sim 1 \text{ V V}\pi$), and high stability.
- Standard fab equipment & methods

Polymer Plus™

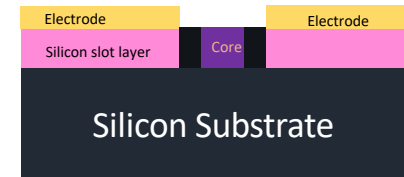


Additive!

Simpler and easier to integrate

- Minimizing polymer layers for integration of modulator with other devices in Si (or other) PIC platform
- Spin-on wafer-level hybrid integration
- Natural integration with PDK of silicon foundries

Polymer Slot™



Tiny!

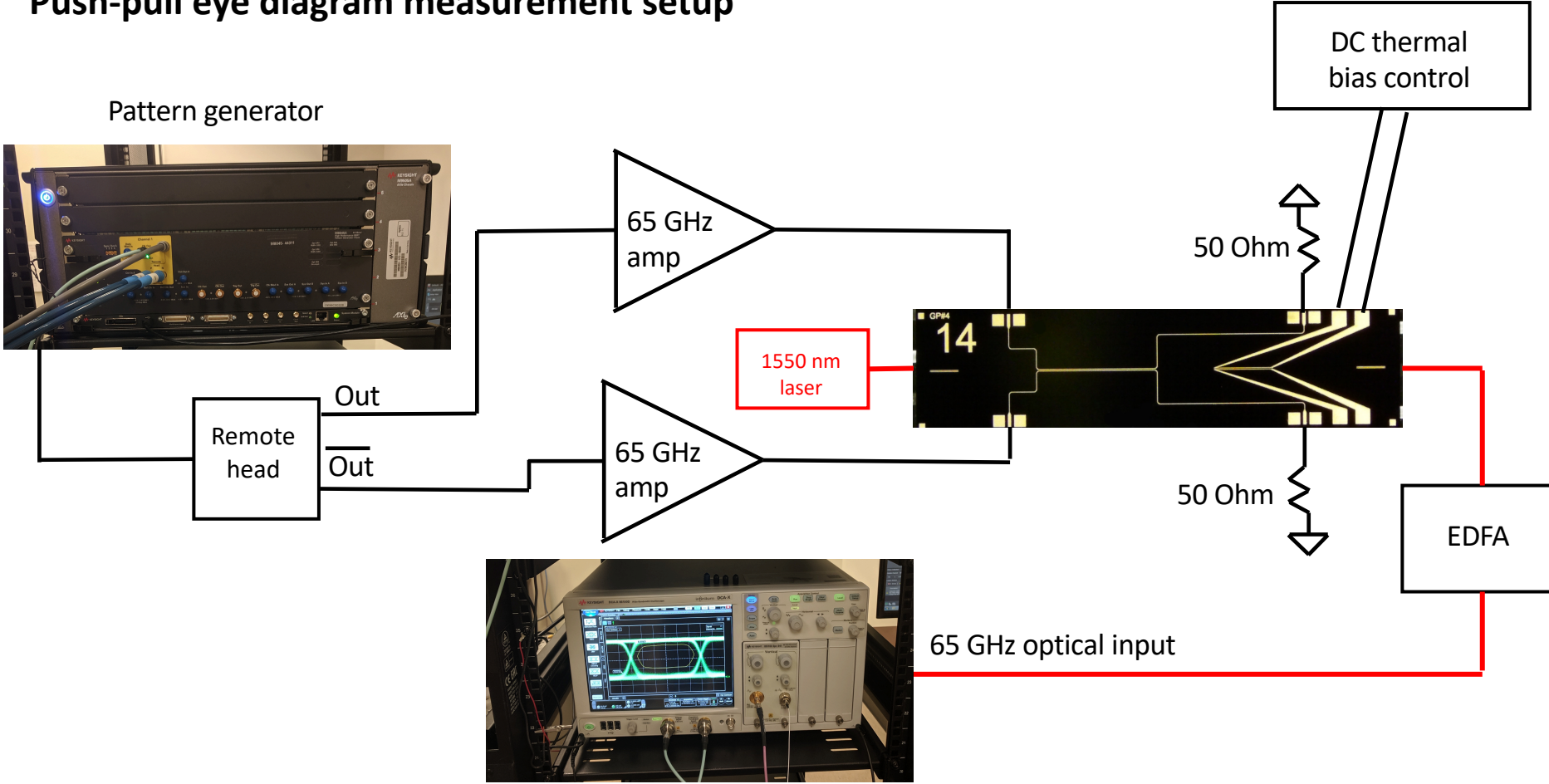
Polymers in Si slot modulators

- Small size for highest integration levels
- Modulator device itself is hybrid silicon-EO Polymer (Silicon provides the waveguiding and electric field, EO polymer provides the high-speed EO functionality)
- Natural integration with PDK of silicon foundries

Turbo-charge your silicon photonics & integrated photonics with polymers...

Test set up

Push-pull eye diagram measurement setup

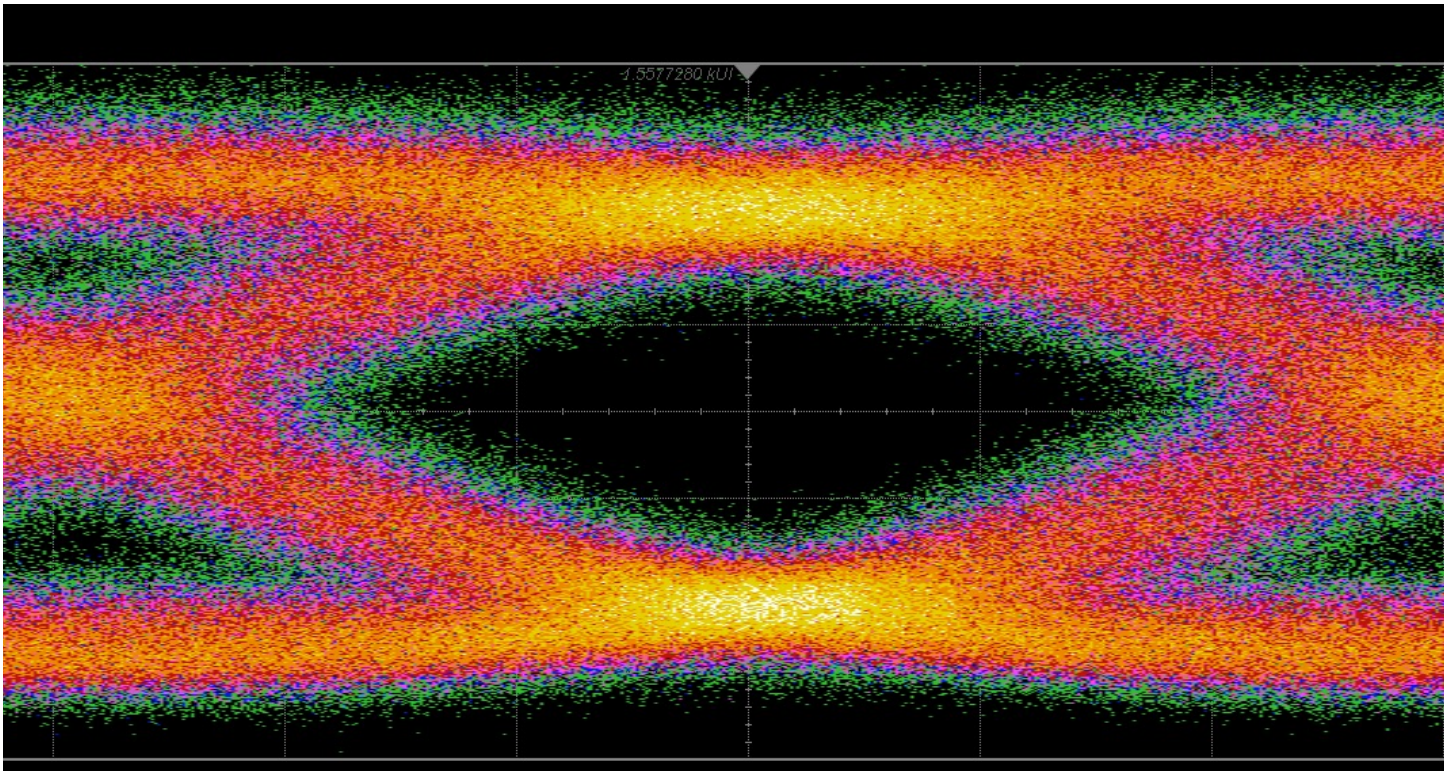


Sampling oscilloscope/digital component analyzer

High speed test set-up at 65GHz push-pull

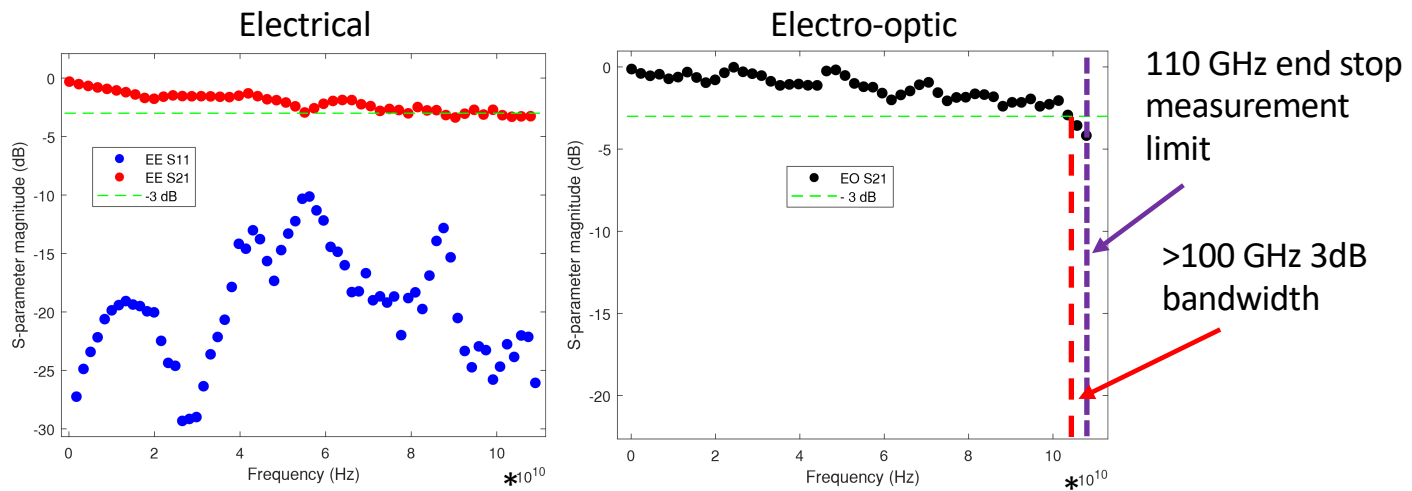
65GHz open eye

Push-pull drive voltage typically < 4V
ER typically > 5 dB
65 GHz (maximum BERT frequency)



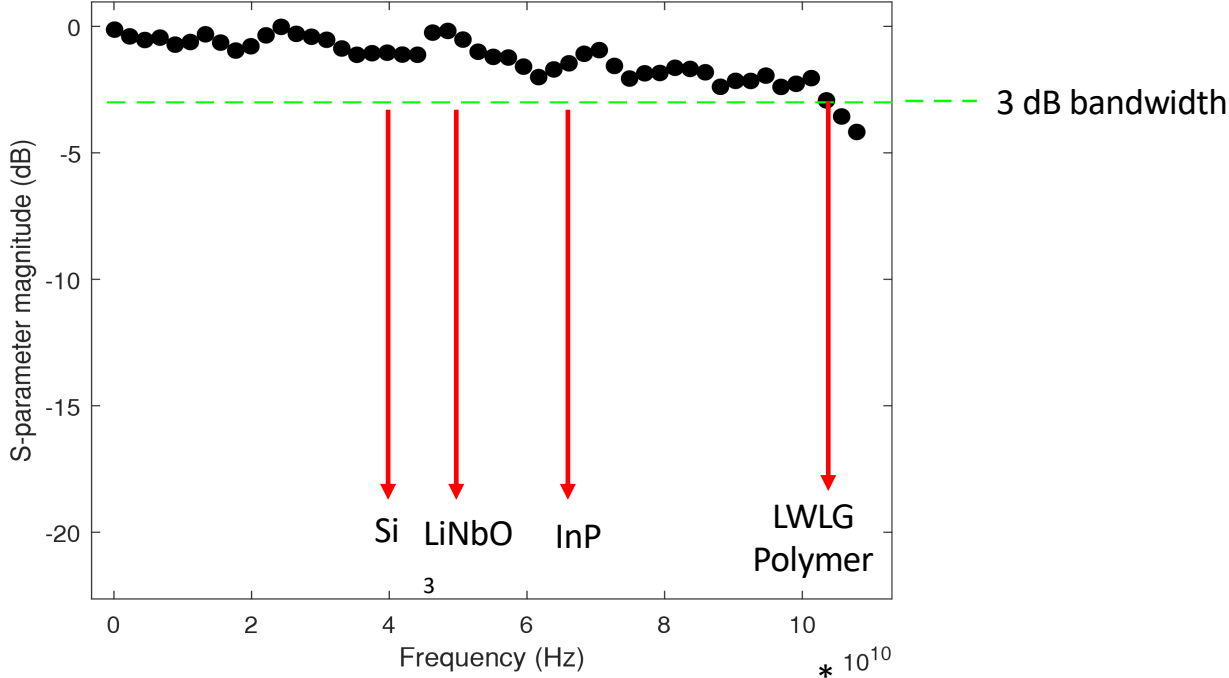
65GHz at the limit of the pulse generator

Recent high-frequency S-parameter data from polymer modulators



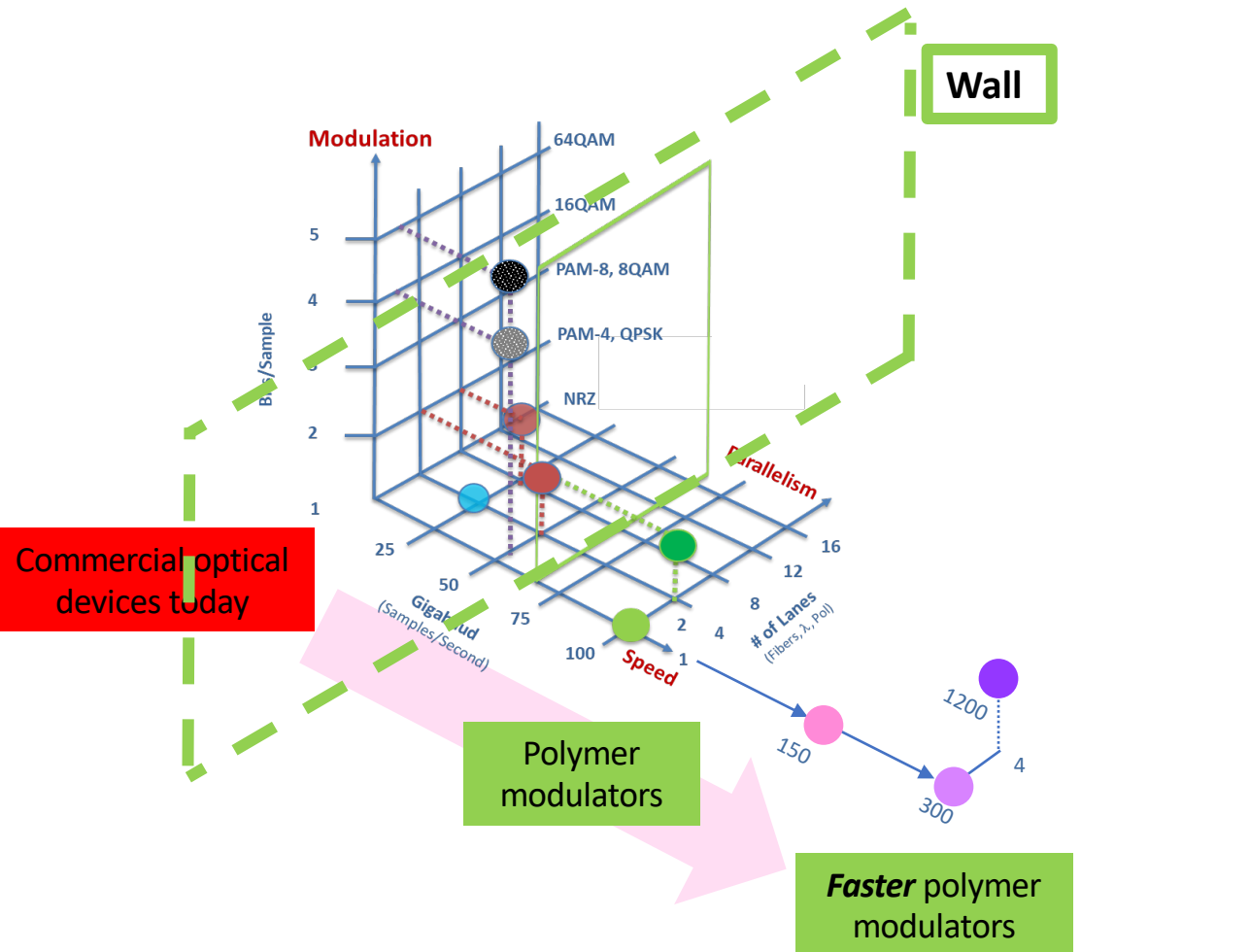
Super high performance > 100GHz S21 EO 3dB bandwidth

Relative comparison of modulators



Polymer modulators outperform competitive semiconductor technologies

Our technology breaks through the wall...



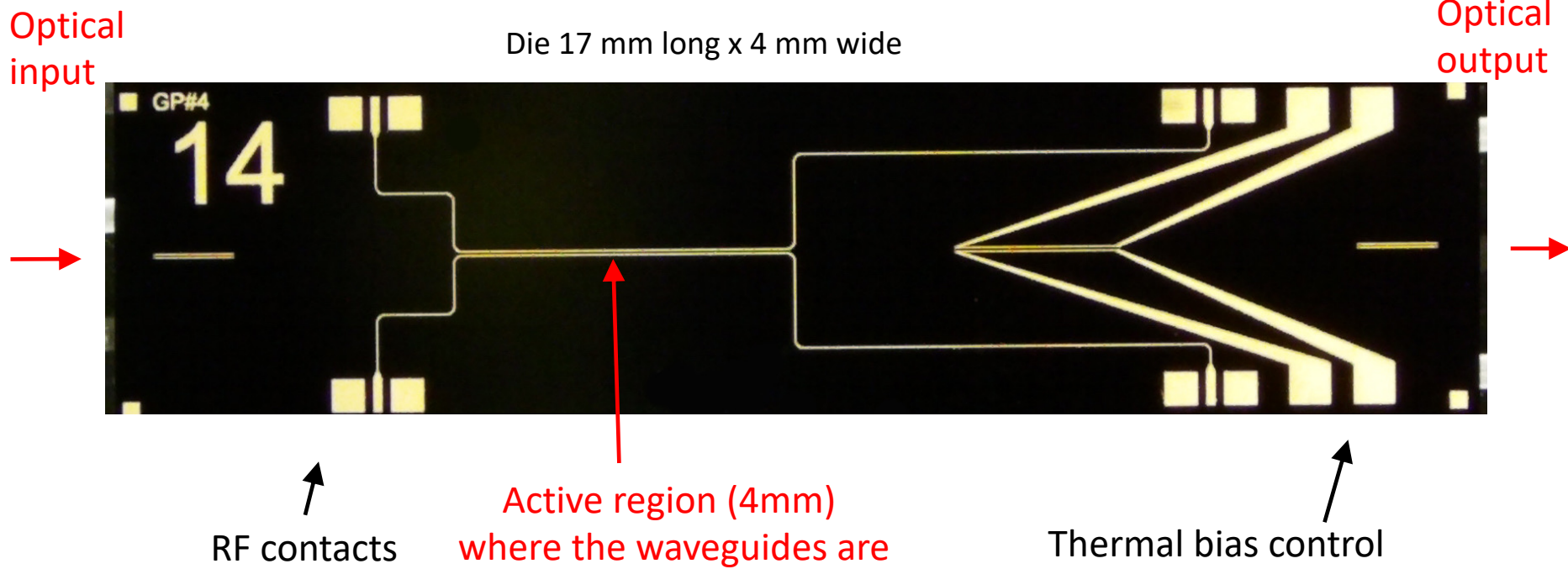
Data rates after breaking through the wall...

- 100Gbps = 100Gbaud, NRZ, 1 lane
- 800Gbps = 100Gbaud, PAM4, 4 lanes
- 150Gbps = 150Gbaud, NRZ, 1 lane
- 300Gbps = 150Gbaud, PAM4, 1 lane
- 1200Gbps = 150Gbaud, PAM4, 4 lanes

Polymers are 3X faster...

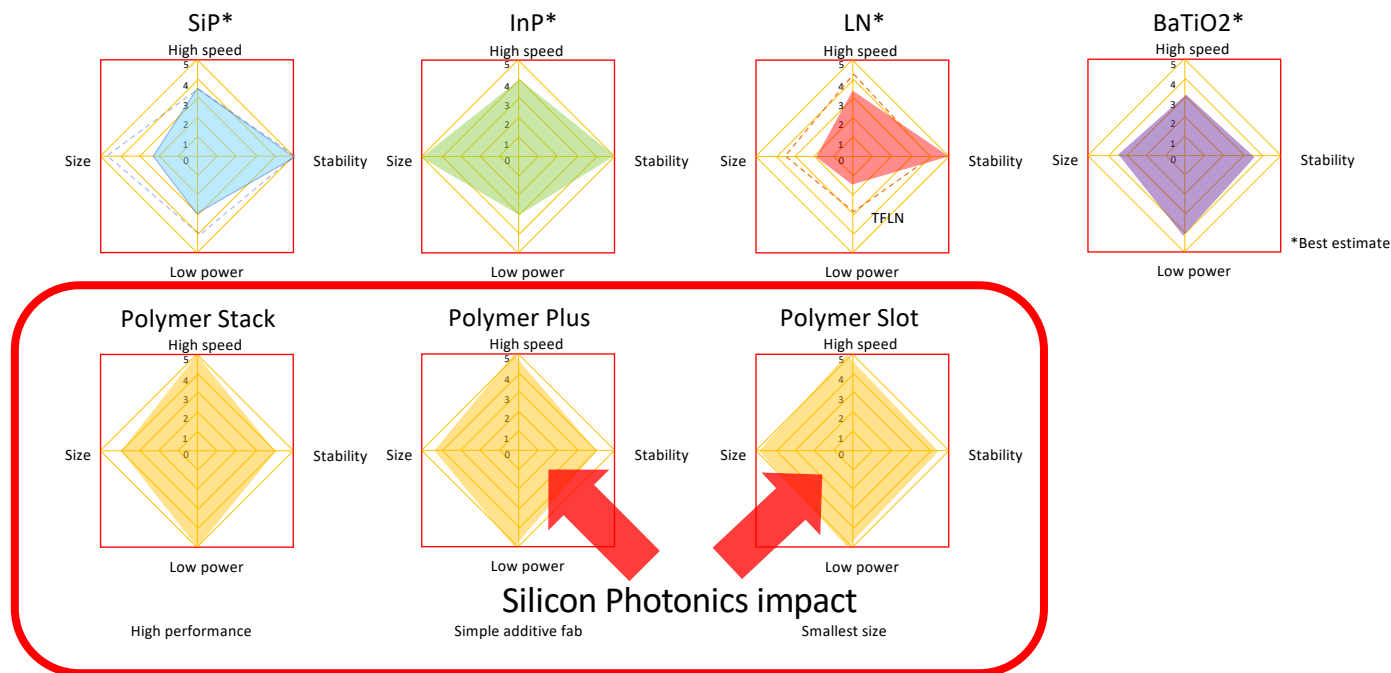
Polymer has head-room to go *much much* faster than competition

Polymer modulator chip



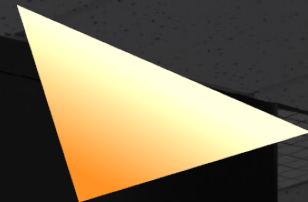
Polymer optical modulator chip fabricated on silicon wafers

Polymer attributes are impressive...



- **Polymer Stack** - traditional design. Very high performance
- **Polymer Plus** - additive to SiPh PICs. Simple fabrication
- **Polymer Slot** - smallest form factor. Ideal for SiPh

Technology strengths and weaknesses → polymer platforms are attractive



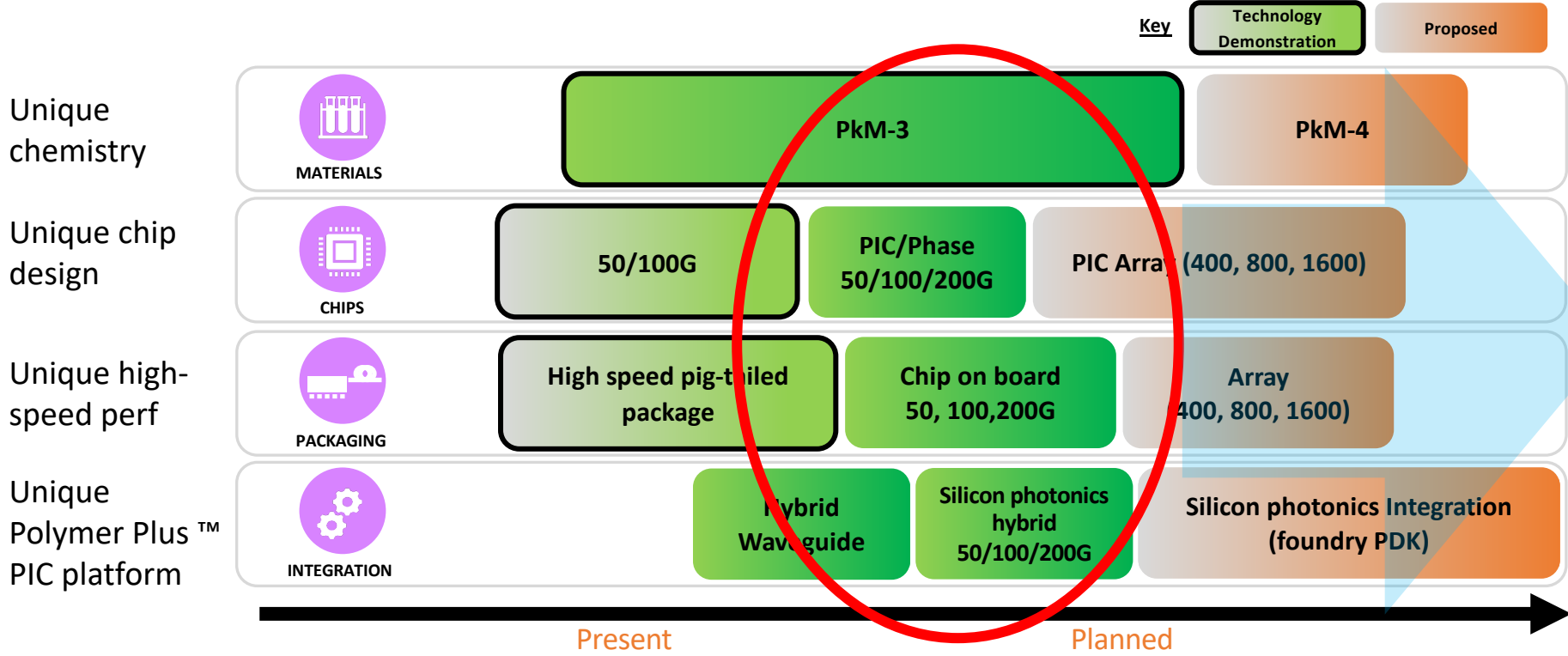
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Foundry scaling

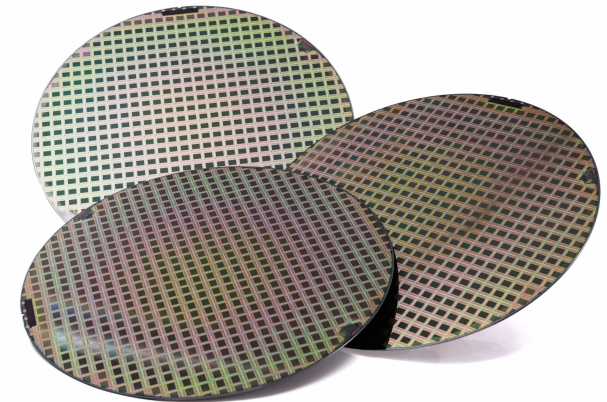


Technology roadmap



Our technology roadmap emphasizes our unique value to the industry

- Process Development Kit (PDK) *to include polymers*
 - PDK is a library or set of building blocks used to lay out your idea into a photonic integrated circuit
 - PDK is provided by the foundry in SiPh
 - PDK allows you to create innovative designs and ramp volume quickly...*perfect vehicle for polymers*



© imec

PDKs are the route to partner with foundries

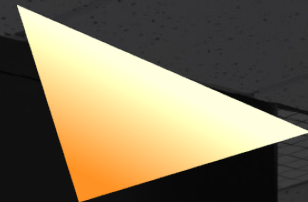
Silicon foundries are hungry for 'opto' business

- CMOS fabrication plants want silicon photonics...new upside
- PDKs will drive the hybrid integration of PIC platforms



Drive to 200/300mm allows competitive PIC cost/volume and scale

*PDK = Process Development Kit



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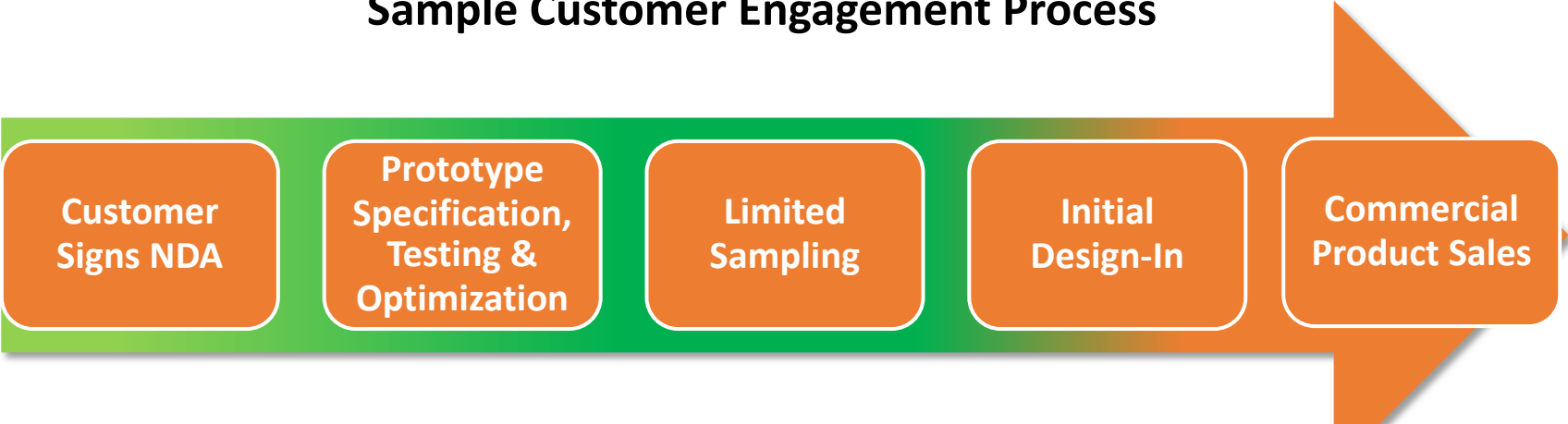
Intellectual Property



Multi-Pronged Business Model:



Sample Customer Engagement Process



3-pronged business model with customer engagement process...

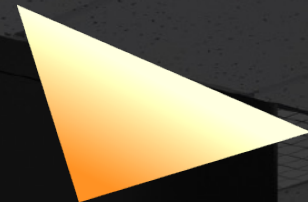
70+ Patents & Patent Applications

Freedom of manufacturing
Technology transfer (large foundries)
Licensing royalties (OEM, CM, Comms customers)



ISSUED	ISSUED	INTERNATIONAL
Heterocyclical chromophore architectures	Polymer modulator devices Fab, high speed, PIC, pkg	USA, EU, Canada, Japan and China
PUBLISHED	ACQUIRED	FILING
Advanced polymer/ silicon photonics materials, devices inventions	Lumera/Gigoptix Patent portfolio (15 Patents)	Innovative polymers Silicon photonics

Powerful patent portfolio with freedom of manufacturing

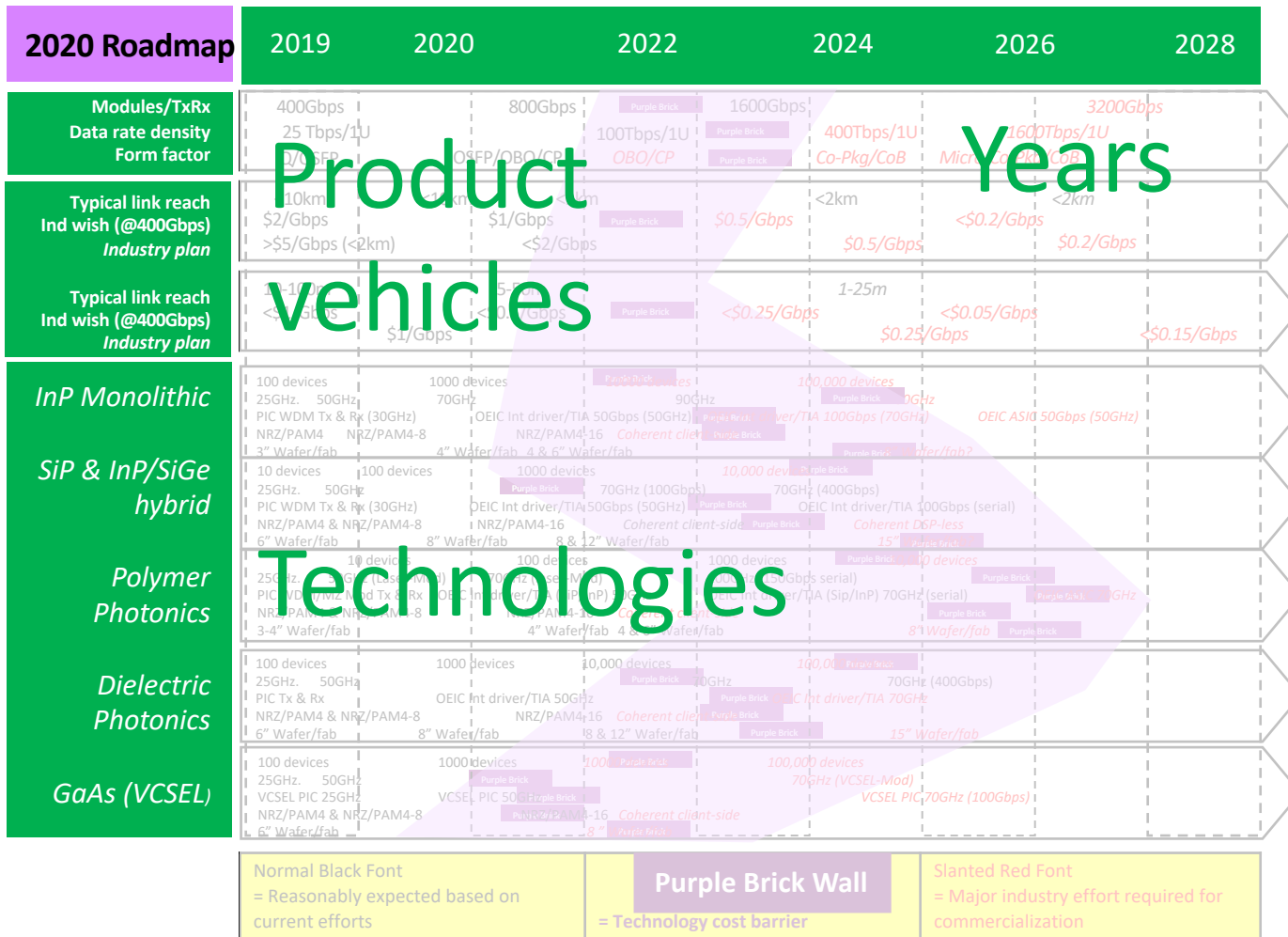


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Roadmaps

(as per Nostradamus...)



Tough to design
>1600Gbps+
TxRx
modules...

Tough to design
>70GHz
bandwidth
devices...

Some
technologies have
higher
performance....

How to scale
PIC
integration?

Simple metrics

Sources: LWLG, iNEMI, AIM Photonics, Photon Delta

2020 Roadmap	2019	2020	2022	2024	2026	2028
Modules/TxRx Data rate density Form factor	400Gbps 25 Tbps/1U Q/OSFP	800Gbps OSFP/OBO/CP	1600Gbps OBS/CP	3200Gbps 400Tbps/1U Co-Pkg/CoB	6400Gbps 1600Tbps/1U Micro-Co-Pkg/CoB	12800Gbps
Typical link reach Ind wish (@400Gbps) Industry plan	<10km \$2/Gbps >\$5/Gbps (<2km)	<10km \$1/Gbps <\$2/Gbps	<2km \$0.5/Gbps	<2km \$0.2/Gbps 1-25m	<2km \$0.2/Gbps	<2km \$0.2/Gbps
Typical link reach Ind wish (@400Gbps) Industry plan	10-100m <\$1/Gbps	5-50m <\$0.5/Gbps \$1/Gbps	<\$0.25/Gbps	<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
<i>InP Monolithic</i>	100 devices 25GHz, 50GHz PIC Tx & Rx (30GHz) NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8 & 12" Wafer/fab	1000 devices 90GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8 & 12" Wafer/fab	10,000 devices 100GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8 & 12" Wafer/fab	100,000 devices 150GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8 & 12" Wafer/fab	1,000,000 devices 200GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8 & 12" Wafer/fab
<i>SiP & InP/SiGe hybrid</i>	10 devices 25GHz, 50GHz PIC WDM/MZ Mod Tx & Rx NRZ/PAM4 & NRZ/PAM4-8 3-4" Wafer/fab	100 devices 70GHz (laser-Mbd) OEIC Int driver/TIA (SiP/InP) 50Gbps NRZ/PAM4-16 4" Wafer/fab	1000 devices 100GHz (15 Gbps serial) OEIC Int driver/TIA (SiP/InP) 70Gbps NRZ/PAM4-16 4" Wafer/fab	10,000 devices 150GHz (400Gbps) OEIC Int driver/TIA 70Gbps NRZ/PAM4-16 4" Wafer/fab	100,000 devices 200GHz (400Gbps) OEIC Int driver/TIA 70Gbps NRZ/PAM4-16 4" Wafer/fab	1,000,000 devices 250GHz OEIC Int driver/TIA 70Gbps NRZ/PAM4-16 4" Wafer/fab
<i>Polymer Photonics</i>	100 devices 25GHz, 50GHz VCSEL PIC 25GHz NRZ/PAM4 & NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz VCSEL PIC 50GHz NRZ/PAM4-16 4" Wafer/fab	1000 devices 100GHz VCSEL PIC 50GHz NRZ/PAM4-16 4" Wafer/fab	10,000 devices 150GHz VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 4" Wafer/fab	100,000 devices 200GHz VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 4" Wafer/fab	1,000,000 devices 250GHz VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 4" Wafer/fab
<i>Dielectric Photonics</i>	100 devices 25GHz, 50GHz PIC Tx & Rx (30GHz) NRZ/PAM4 & NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 4" Wafer/fab	1000 devices 100GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 4" Wafer/fab	10,000 devices 150GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 4" Wafer/fab	100,000 devices 200GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 4" Wafer/fab	1,000,000 devices 250GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 4" Wafer/fab
<i>GaAs (VCSEL)</i>	100 devices 25GHz, 50GHz VCSEL PIC 25GHz NRZ/PAM4 & NRZ/PAM4-8 3-4" Wafer/fab	1000 devices 70GHz VCSEL PIC 50GHz NRZ/PAM4-16 4" Wafer/fab	1000 devices 100GHz VCSEL PIC 50GHz NRZ/PAM4-16 4" Wafer/fab	10,000 devices 150GHz VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 4" Wafer/fab	100,000 devices 200GHz VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 4" Wafer/fab	1,000,000 devices 250GHz VCSEL PIC 70GHz (100Gbps) NRZ/PAM4-16 4" Wafer/fab
	Normal Black Font = Reasonably expected based on current efforts		Purple Brick Wall = Technology cost barrier		Slanted Red Font = Major industry effort required for commercialization	

Normal R&D funding

Major investment in R&D to achieve goals

Tough to design >1600Gbps+ TxRx modules...

Tough to design >70GHz bandwidth devices...

Some technologies have higher performance....

How to scale PIC integration?

Red means major industry efforts needed for commercialization

2020 Roadmap	2019	2020	2022	2024	2026	2028
Modules/TxRx	400Gbps	800Gbps	1600Gbps	3200Gbps	6400Gbps	12800Gbps
Data rate density	25 Tbps/1U	50 Tbps/1U	100 Tbps/1U	200 Tbps/1U	400 Tbps/1U	800 Tbps/1U
Form factor	Q/OSFP	OSFP/OBO/CP	OBO/CP	Co-Pkg/CoB	Micro-Co-Pkg/CoB	
Typical link reach	<10km	<10km	<2km	<2km	<2km	<2km
Ind wish (@400Gbps)	\$2/Gbps	\$1/Gbps	\$0.5/Gbps	\$0.25/Gbps	\$0.1/Gbps	\$0.05/Gbps
Industry plan	>\$5/Gbps (<2km)					
Typical link reach	10-100m		5-50m	1-25m		
Ind wish (@400Gbps)	<\$1/Gbps	\$1/Gbps	<\$0.5/Gbps	<\$0.25/Gbps	<\$0.05/Gbps	<\$0.15/Gbps
Industry plan						
InP Monolithic	100 devices 25GHz, 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 3" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4" Wafer/fab	10,000 devices 90GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4" Wafer/fab	100,000 devices 100GHz OEIC Int driver/TIA 100Gbps (serial) Coherent client-side 4" & 6" Wafer/fab	1,000,000 devices 140GHz OEIC Int driver/TIA 100Gbps (serial) Coherent client-side 8" Wafer/fab	10,000,000 devices 200GHz OEIC Int driver/TIA 100Gbps (serial) Coherent client-side 15" Wafer/fab
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Purple brick wall = Technology cost barrier

- Tough to design >1600Gbps+ TxRx modules...
- Tough to design >70GHz bandwidth devices...
- Some technologies have higher performance....
- How to scale PIC integration?

We may have photonics technology → but not at a cost for commercialization

- Huge amount of data and small font...1-page...
- Details can be better viewed better *online*

Roadmaps provide a vehicle for all stakeholders: Gvt, industry, academia, bankers and investors...

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Modules/TxRx Data rate density Form factor	400Gbps 25 Tbps/1U Q/OSFP	800Gbps OSFP/OBO/CP	100Tbps/1U OBO/CP	1600Gbps Co-Pkg/CoB	400Tbps/1U Micro-Co-Pkg/CoB	3200Gbps 1600Tbps/1U
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InP Monolithic	100 devices 25GHz, 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 3" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-8 4" Wafer/fab	1000 devices 90GHz OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4 & 6" Wafer/fab	100,000 devices 100GHz OEIC Int driver/TIA 100Gbps (70GHz) Coherent client-side 6" Wafer/fab	100,000 devices 100GHz OEIC Int driver/TIA 100Gbps (70GHz) Coherent DSP-less 8" Wafer/fab	100,000 devices 100GHz OEIC ASIO 50Gbps (50GHz) 15" Wafer/fab?
SiP & InP/SiGe hybrid	10 devices 25GHz, 50GHz PIC WDM Tx & Rx (30GHz) NRZ/PAM4 & NRZ/PAM4-8 6" Wafer/fab	100 devices 70GHz (laser-Mbd) OEIC Int driver/TIA (SiP/InP) 50GHz NRZ/PAM4-16 8" Wafer/fab	1000 devices 70GHz (100Gbps) OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 8 & 12" Wafer/fab	10,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 100Gbps (70GHz) Coherent DSP-less 8" Wafer/fab	10,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 100Gbps (70GHz) Coherent DSP-less 15" Wafer/fab	10,000 devices 70GHz (400Gbps) OEIC Int driver/TIA 100Gbps (70GHz) Coherent DSP-less 15" Wafer/fab
Polymer Photonics	10 devices 25GHz, 50GHz (Laser-Mod) PIC WDM/MZ Mod Tx & Rx NRZ/PAM4 & NRZ/PAM4-8 3-4" Wafer/fab	100 devices 70GHz (laser-Mbd) OEIC Int driver/TIA (SiP/InP) 50GHz NRZ/PAM4-16 4" Wafer/fab	1000 devices 70GHz (100Gbps) OEIC Int driver/TIA 50Gbps (50GHz) NRZ/PAM4-16 4 & 6" Wafer/fab	1000 devices 100GHz (150Gbps serial) OEIC Int driver/TIA (SiP/InP) 70GHz (serial) Coherent DSP-less 8" Wafer/fab	1000 devices 100GHz (150Gbps serial) OEIC Int driver/TIA (SiP/InP) 70GHz (serial) Coherent DSP-less 15" Wafer/fab	1000 devices 100GHz (150Gbps serial) OEIC Int driver/TIA (SiP/InP) 70GHz (serial) Coherent DSP-less 15" Wafer/fab
Dielectric Photonics	100 devices 25GHz, 50GHz PIC Tx & Rx NRZ/PAM4 & NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz OEIC Int driver/TIA 50Gbps NRZ/PAM4-16 8 & 12" Wafer/fab	100,000 devices 70GHz OEIC Int driver/TIA 70GHz Coherent client-side 15" Wafer/fab	100,000 devices 70GHz OEIC Int driver/TIA 70GHz Coherent client-side 15" Wafer/fab	100,000 devices 70GHz OEIC Int driver/TIA 70GHz Coherent client-side 15" Wafer/fab
GaAs (VCSEL)	100 devices 25GHz, 50GHz VCSEL PIC 25GHz NRZ/PAM4 & NRZ/PAM4-8 6" Wafer/fab	1000 devices 70GHz VCSEL PIC 50Gbps NRZ/PAM4-16 8" Wafer/fab	10,000 devices 70GHz VCSEL PIC 50Gbps NRZ/PAM4-16 8" Wafer/fab	100,000 devices 70GHz (VCSEL-Mod) VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab	100,000 devices 70GHz (VCSEL-Mod) VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab	100,000 devices 70GHz (VCSEL-Mod) VCSEL PIC 70GHz (100Gbps) Coherent client-side 8" Wafer/fab
Normal Black Font = Reasonably expected based on current efforts		Purple Brick Wall = Technology cost barrier		Slanted Red Font = Major industry effort required for commercialization		

Tough to design >1600Gbps TxRx modules...

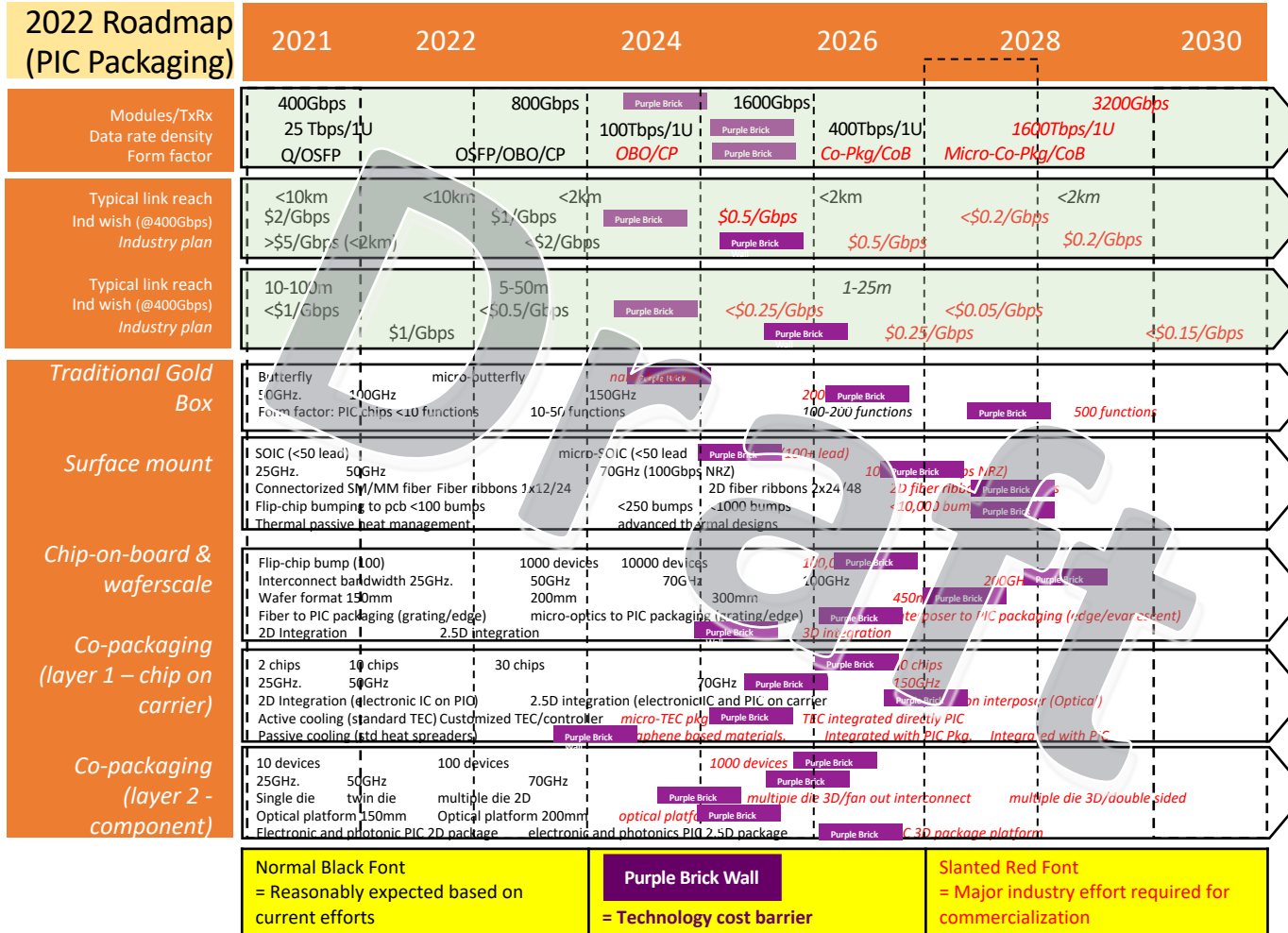
Tough to design >70GHz bandwidth devices...

Some technologies have higher performance....

Where we penetrate the 'Purple Brick Wall'?

- A *1-page PIC packaging roadmap*...
- Details can be better viewed better *online*

Simple 1-slide roadmaps – have impact

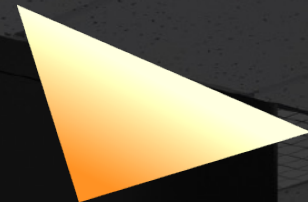


1 page roadmap...

Still in draft form...

Evolving document...

A PIC packaging roadmap...



LIGHTWAVELOGIC™

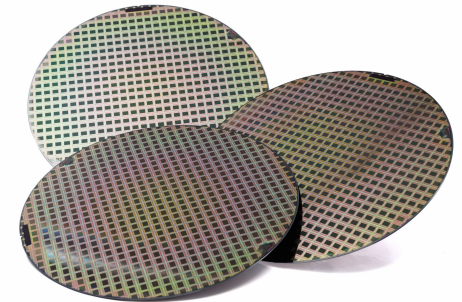
Faster by Design

Summary



Partnering for success

- Our technology platform that is working to help scale existing internet structure (enabling technology)
- Technology designed to transmit data at higher speeds with less power (with 3dB optical bandwidths in excess of 100GHz)
- Leveraging internally-engineered electro-optic (EO) polymers to create photonic devices that convert data from electrical signals into optical signals
- Working with multiple foundries, module/packaging partners to position Lightwave for future high-volume production
- Technology roadmaps guide us all...packaging is next



© imec



Leveraging our partners to commercialize our technology in polymers

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